



and Applications



Introduction

Basic Switch Types and Applications

Switch Function - Mechanical

Poles and Throws, Mechanical Characteristics

Switch Function - Electrical

Voltage and Current Ratings, Contact Resistance

Process Applications

Hand Solder, Wave Solder, SMT



Basic Switch Types

Push-Button and Toggle Switches

- Power Switches
- Slide Switches
- Rotary Switches
- Key Lock Switches
- Tact Switches and Domes





Tact Switches and Domes

• **TYPICAL APPLICATIONS**

• Low power, miniature devices, digital switching - pda's, cell phones etc.

• Tactile operator feedback required- switch confirmation, felt "click" when the switch is depressed

• Long life typically required, SMT and wash tight capability





Push-button and Toggle Switches

• **TYPICAL APPLICATIONS**

• Medium power, bench-size devices, analog switching - audio, measurement equipment etc.

• Mechanical latching operation and Agency Approvals option

• Design typically has substantial amount of self-cleaning capability due to contact wipe action





Power Switches

• **TYPICAL APPLICATIONS**

• High power, on-off switching, consumer, industrial - audio, measurement equipment etc.

• Mechanical latching operation typical, indicator lighting option

Most are "snap action" type construction, with minimal contact wipe

• Agency approvals required (UL, CSA, CE etc.)







Slide Switches

• TYPICAL APPLICATIONS

• Low power, on-off switching, consumer, industrial - audio, measurement equipment, toys, low-cost applications etc.

- Self cleaning contacts due to wiping action (typically)
- Unique switching contact groups available





Rotary Switches

• TYPICAL APPLICATIONS

• Low power, on-off switching, digital, industrial - audio, measurement equipment etc.

- Several contact groupings available, up to 4 poles
- Self cleaning contacts, due to wiping action







Key Lock Switches

• **TYPICAL APPLICATIONS**

- High power, on-off switching, consumer, industrial safety lockout capability
- Multiple positions available
- Most are "sliding action" type construction, with substantial contact wipe
- Agency approvals available (UL, CSA, CE etc.)





<u>Switch Function Mechanical</u> Switch Construction - Poles and Throws

- Most Common
- Single Pole Single Throw, Single Pole Double Throw
- Double Pole Single Throw
- Double Pole Double Throw

Single-Pole Double-Throw Double-Break	Double-Pole Double-Throw Double-Break	
Single-Pole Single-Throw Single-Break	 Double-Pole Single-Throw Single-Break	
Single-Pole Single-Throw Double-Break	Double-Pole Single-Throw Double-Break	
Single-Pole Double-Throw Single-Break	 Double-Pole Double-Throw Single-Break	

Switch Function Mechanical

FORCE / DEFLECTION CURVE - Tact or Dome



Switch Function Mechanical

• FORCE / DEFLECTION CURVE - Push Button



Switch Function Mechanical

FORCE / DEFLECTION CURVE - Snap Action





Switch Function Electrical

- CONTACT RATING
- Volts AC or Volts DC measured in VAC or VDC
- Current Rating measured in milliamps or amps
- Electrical Life (cycles under load)
- Contact Resistance milli-ohm measurement
- Contact Material gold or silver (typically alloyed)



Switch Function Electrical

- INSULATION RATING
- Insulation Resistance Meg-ohms
- Dielectric Withstanding Volts AC or DC
- (Dielectric Withstanding) High-pot



HAND SOLDER

- 15 30 watt solder iron typical
- Typical solder iron tip temperature 650-700 F
- Typical solder dwell time 3 seconds
- No-clean fluxes generally used, if not, cleaning is required (bottom-side only)



• WAVE SOLDER

- Typical solder temperature 500 F. (260 C.)
- Typical solder dwell time 3 seconds
- Typical belt speed 20 inches/minute
- Typical preheat temperature 266 F. (130 C.)
- OA (organic acid) water wash fluxes generally used
- Water wash or hand cleaning required

• **TYPICAL WAVE SOLDER EQUIPMENT**



- WAVE ZONES (3)
- FLUX
- PREHEAT
- WAVE SOLDER





SMT

- Typical max temp 464 F (240 C)
- Typical belt speed 20 inches/minute
- No-clean or OA fluxes typically used





•PICK & PLACE





• **SMT** TYPICAL SOLDER REFLOW PROFILE



Table 1. Lead-Free Reflow Profile Parameters

Profile Parameter	Lead-Free Assembly, Convection, IR/Convection	
Ramp-up rate (Tsmax to Tp)	3 °C/second max.	
Preheat temperature (Tsmin to Tsmax)	150 °C to 200 °C	
Preheat time (ts)	60 - 180 seconds	
Time above T _L , 217 °C (t _L)	60 - 150 seconds	
Peak temperature (Tp)	240 C - Typical (464 F)	
Time within 5 °C of peak temperature (1p)	20 - 40 seconds	
Ramp-down rate	6 °C/second max.	
Time 25 °C to peak temperature	8 minutes max.	



- **SMT** TYPICAL SOLDER REFLOW PASTE
 - **Sn/Ag/Cu** (tin, silver, copper)
 - 95.5/3.9/0.6 Solid 216 C / Liquid 217 C (422 F)

(Sn/Pb – 63/37) – Solid 182 C / Liquid 183 C (362 F)

• TYPICAL WATER WASH (high-pressure water)

- Requires "WASH SEALED" switch, typical wash temp 150 F
- Typical Zones -- PREWASH -- WASH -- WASH -- RINSE -- DRY



Introduction

Basic Switch Categories

Non-Sealed

No Special Construction To "Seal" Switch

• Flux Resistant

Typically Epoxy or RTV Used To Seal Terminals

• Wash Tight

Switch Construction Specifically Designed To Allow Machine Washing

Switch Types

Non-Sealed

NO SPECIAL SWITCH CONSTRUCTION TO PREVENT FLUID ENTRY



Switch Types

Flux Resistant



Switch Types

Wash Tight (TL6700, TL6100, TL6110, TL6120, 100A, 200A, 200B, 300A, 400A)

SWITCH SPECIFICALLY DESIGNED TO PREVENT WASH WATER ENTRY



Note : "Wash Tight" is NOT the same as "WATERPROOF".

"Wash Tight" is intended to provide protection from water entry into the switch, under reasonable wash conditions. The ability of the switch to pass this criteria is based upon test data from the MIL-STD-202E Heated Fluorocarbon Immersion Test. This test cannot guarantee performance in all wash conditions, due to the wide range of varying machine conditions. Our testing indicates 40 PSIG wash pressure can be tolerated.

Seal Test Standards

- IP 40 (sealed against solid objects > 1 mm dia.)
- IP 50 (dust protected)
- IP54 (dust protected / splashing water protected)
- IP 60 (dust tight)
- IP 64 (dust tight / splashing water protected)
- IP 65 (dust tight / water jet protected)
- IP 67 (dust tight / water immersion protected)

Seal Test Standards

• MIL-Std-883C Method 1011 Test Condition A

Immersion in a +100 degree C. water bath -- 5 minutes Immediately transfer to 0 degree C. water bath -- 5 minutes REPEAT ABOVE 10 CYCLES Measure Insulation Resistance Before and After Immersion Disassemble Switch After and Examine For Evidence of Water

* Destructive Test (Most suited for design and R&D)

Seal Test Standards

<u>MIL-Std-202E Method 112 Test Condition D</u>

Immersion in a Fluorocarbon Liquid at +125 C for 20 Seconds (note : a lower temp. (max. temp. the switch is rated for) may be necessary A Steady Stream of Bubbles From The Switch Indicates a Leak

* Preferred Test Method (Non-Destructive, most suitable for production testing)



"Process Sealed" Benefits

- Switch Processed Normally With Other Standard Components (SIGNIFICANT COST-REDUCTION DUE TO REDUCED HANDLING AND TIME)
- Enhanced Contact Reliability Due To Sealing

(LONG-TERM CONTACT PERFORMANCE BENEFIT)



Seal Testing

Preferred Method - Heated Fluorinert Bath



MIL-Std-202E Method 112 Test Condition D

A Fluorinert liquid bath is heated to 125 degrees C., or the switch maximum operating temperature, (usually 85 degrees C.). The device under test is lowered into the heated bath, causing the trapped air inside the device to expand. Any substantial leak path can then be readily identified by a stream of bubbles escaping from the switch body. The standard test time is 60 seconds, but may be reduced to 30 seconds for high-volume production testing, as failures typically occur within 15 - 20 seconds after submersion.

Passing of this test results in a switch that will meet most solder and wash processes, but unique wash circumstances will still prevail, and can lead to switch failures, such as extreme wash pressures, temperatures, thermal shock, etc. Correlation between the test and the actual wash process may be required.

E-SWITCH® Switch Glossary of Terms

Actuator: The mechanical interface between the basic switch contacts and the means of operation, such as the operator's finger.

Actuation Force: The required force to change a circuit's electrical state.

Alternate Action Switch: A Pushbutton style switch where the change of the electrical state is maintained between actuations

Ampere: A unit of electrical current flow

Break Before Make: The term given to a double throw switch where the first circuit is opened before the second circuit is closed

Contact Bounce: Oscillation of the movable contact upon closure of the circuit

Contact Resistance: The resistance of current flow across closed contacts

Dielectric strength: The ability of an insulating material to resist voltage from arcing across it's surface.

Insulation resistance: The resistance to current flow of the insulating materials between contacts

Make Before Break: The term given to a double throw switch when the second circuit is closed before the first circuit is opened

Switch Glossary of Terms

Momentary Action Switch: The term given to a switch where a circuit is continuously closed or open only when force is applied. The electrical state returns to it's normal position when the force is removed.

Normally Closed: The term given to a switch where a circuit is closed in the normal switch position

Normally Open: The term given to a switch where a circuit is open in the normal switch position

Over Travel: The distance an actuator travels after the circuit is closed

Pole: The term to denote a completely separate circuit, which passes through a switch at one time

Pre Travel: The movement of the actuator prior to closing the circuit

Throw: The term denotes the number of positions in which a given pole is closed

Travel to Make: The distance parallel to the designated direction of the actuator movement at which point a circuit is closed

Switch Abbreviations:

Normally Closed circuit N.C. Normally Open circuit N.O. SPST Single Pole Single Throw Single Pole Double Throw SPDT Double Pole Single Throw DPST Double Pole Double Throw DPDT MBB Make Before Break BBM Break Before Make